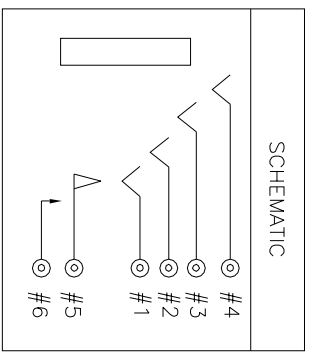
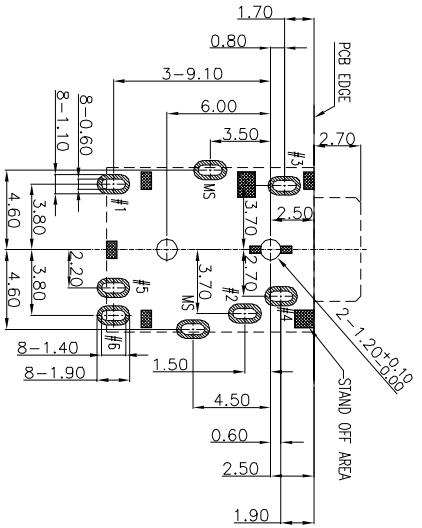


RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE: ±0.05)



REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: C140715-9A	MARS	2014.09.12
B	ECN NO: S180821-C	JIE-FU	2016.09.13

- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
 - CONTACT RESISTANCE: 50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES.
 - INSERTION FORCE: 0.3 - 3.0kg.
 - WITHDRAWAL FORCE: 0.3 - 3.0kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK " " ON TOP OF CONNECTOR.
 - PACKAGING : TRAY.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ♻️
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: ♻️

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
J	MYLAR	1	MYLAR 0.075I	TRANSPARENT
I	SHELL	1	COPPER ALLOY, 0.2t	NICKEL 60u" MIN. PLATING.
H	SEPERATE	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA, WHITE TIN 120u" ON SOLDER TAIL, ALL OVER NICKEL 50u" MIN. PLATING.
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA, ALL OVER NICKEL 50u" MIN. PLATING.
E	TIP SPRING	1	COPPER ALLOY, 0.25t	
D	RING-A	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA,
C	RING-B	1	COPPER ALLOY, 0.2t	WHITE TIN 120u" ON SOLDER TAIL,
B	EARTH	1	COPPER ALLOY, 0.2t	ALL OVER NICKEL 50u" MIN. PLATING.
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	

TITLE	PART NO.	SCALE	UNIT	SHEET	REV.
φ3.50 AUDIO JACK	2SJ3082-031112F	4:1	mm	1 OF 1	B

Singatron Enterprise Co., Ltd.
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